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TRANSMITTAL

SIR:

Further to the electronic filing on April 2, 2009 of a supplemental information disclosure statement, and the Examiner's notation in the Notice of Allowance regarding same in the above-identified application, attached as an add on, please find the translation of Claim 1 to JP 62-219479.

Respectfully submitted,

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Claim 1 from JP-62-219479-A

1. Title of the invention

Gold Plated Contact Material

2. Claims

(1) A gold plated contact material characterized in that, on a clad material, wherein stainless steel cladding has been performed on one side or both sides of a core material comprising copper or a copper alloy, gold plating and/or gold alloy plating is performed on the entire surface or a portion of the surface of said stainless steel.